CD4543B Types

CMOS BCD-to-Seven-Segment Latch/Decoder/Driver For Liquid-Crystal Displays

High-Voltage Types (20-Volt Rating)

Features:
- Display blanking of all illegal input combinations
- Latch storage of code
- Capability of driving two low power TTL loads, two HTL loads, or one low power Schottky load over the full rated-temperature range
- Pin-for-pin replacement for the CD4056B (with pin 7 tied to V_{SS})
- Direct LED driving capability

**CD4543B
TERMINAL ASSIGNMENT**

- CD4543B is a BCD-to-seven segment latch/decoder/driver designed primarily for liquid-crystal display (LCD) applications. It is also capable of driving light emitting diode (LED), incandescent, gas-discharge, and fluorescent displays. This device is functionally similar to and serves as direct replacement for the CD4056B when pin 7 is connected to V_{ss}. It differs from the CD4056B in that it has a display blanking capability instead of a level-shifting function and requires only one power supply. When the CD4056B is used in the level shifting mode, two power supplies are required. When the CD4543B is used for LCD applications, a square wave must be applied to the PHASE input and the backplane of the LCD device. For LED applications a logic 0 is required at the PHASE input for common-cathode devices; a logic 1 is required for common-anode devices (see truth table).

The CD4543B is supplied in 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

- 100% tested for quiescent current at 20 V
- Maximum input current of 1 µA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- Noise margin (full package-temperature range)= 1 V at V_{DD}=5 V
                        2 V at V_{DD}=10 V
                        2.5 V at V_{DD}=15 V
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

Applications:
- Instrument display driver
- Dashboard display driver
- Computer/calculator display driver
- Timing device driver (clocks, watches, timers)

MAXIMUM RATINGS, *Absolute–Maximum Values:*

DC SUPPLY-VOLTAGE RANGE, (V_{DD})
  Voltages referenced to V_{SS} Terminal) .... –0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS .... –0.5V to V_{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT .... ±10mA
POWER DISSIPATION PER PACKAGE (P_D):
  For T_A = –55°C to +100°C 500mW
  For T_A = +100°C to +125°C .... Derate Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
  FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW
OPERATING-TEMPERATURE RANGE (T_A) .... –55°C to +125°C
STORAGE TEMPERATURE RANGE (T_{stg}) .... –65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):
  At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max .... +265°C

Fig. 1 – BCD-to-seven-segment latch/decoder/driver CD4543B logic circuit diagram.

RECOMMENDED OPERATING CONDITIONS at T_A=25°C, Unless Otherwise Specified

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC		V_{DD} (V)	LIMITS		UNITS
			MIN.	TYP.	
Supply-Voltage Range (For T_A=Full Package-Temperature Range)		—	3	18	V
Latch Disable Pulse Width	t_{WH}	5	250	125	ns
		10	100	50	
		15	80	40	
Minimum Data Setup Time	t_{SU}	5	60	15	
		10	20	-5	
		15	10	-5	
Minimum Data Hold Time	t_H	5	25	-5	
		10	20	10	
		15	20	10	

STATIC ELECTRICAL CHARACTERISTICS

CHARAC-TERISTIC		CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)				+25			UNITS
		V_O (V)	V_{IN} (V)	V_{DD} (V)	-55	-40	+85	+125	Min.	Typ.	Max.	
Quiescent Device Current Max.	I_{DD}	—	0, 5	5	5	5	150	150	—	0.04	5	μA
		—	0,10	10	10	10	300	300	—	0.04	10	
		—	0,15	15	20	20	600	600	—	0.04	20	
		—	0,20	20	100	100	3000	3000	—	0.08	100	
Output Low (Sink) Current Min.	I_{OL}	0.4	0, 5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
		0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
		1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	—	
Output High (Source) Current Min.	I_{OH}	4.6	0, 5	5	-0.46	-0.44	-0.30	-0.26	-0.37	-0.75	—	
		2.5	0, 5	5	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	—	
		9.5	0,10	10	-0.98	-0.92	-0.68	-0.55	-0.8	-1.6	—	
		13.5	0,15	15	-3.33	-3.18	-2.2	-1.9	-2.7	-5.4	—	
Output Voltage Low-Level Max.	V_{OL}	—	0, 5	5	0.05				—	0	0.05	V
		—	0,10	10	0.05				—	0	0.05	
		—	0,15	15	0.05				—	0	0.05	
Output Voltage High-Level Min.	V_{OH}	—	0, 5	5	4.95				4.95	5	—	
		—	0,10	10	9.95				9.95	10	—	
		—	0,15	15	14.95				14.95	15	—	
Input Low Voltage Max.	V_{IL}	0.5,4.5	—	5	1.5				—	—	1.5	V
		1, 9	—	10	3				—	—	3	
		1.5,13.5	—	15	4				—	—	4	
Input High Voltage Min.	V_{IH}	0.5,4.5	—	5	3.5				3.5	—	—	
		1, 9	—	10	7				7	—	—	
		1.5,13.5	—	15	11				11	—	—	
Input Current Max.	I_{IN}	—	0,18	18	±0.1	±0.1	±1	±1	—	$\pm 10^{-5}$	±0.1	μA

Fig. 2 – Typical output high (source) current characteristics.
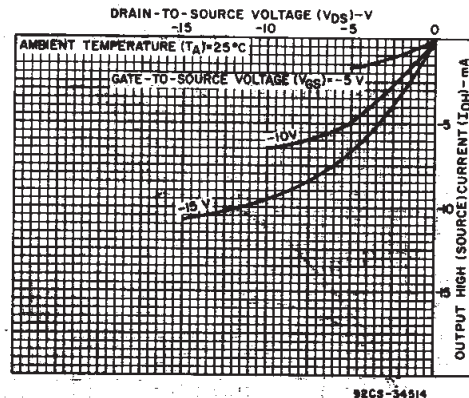

Fig. 3 – Minimum output high (source) current characteristics.

DYNAMIC ELECTRICAL CHARACTERISTICS at T_A=25° C; C_L=50 pF, Input t_r,t_f=20 ns, R_L=200 kΩ

CHARACTERISTIC		TEST CONDITIONS V_{DD} (V)	LIMITS All Packages			UNITS
			MIN.	TYP.	MAX.	
Propagation Delay Time	t_{PHL}	5	—	600	1200	
		10	—	200	400	
		15	—	150	300	
	t_{PLH}	5	—	500	1000	
		10	—	200	400	
		15	—	150	300	
Transition Time	t_{THL}	5	—	180	360	
		10	—	90	180	
		15	—	65	130	ns
	t_{TLH}	5	—	180	360	
		10	—	90	180	
		15	—	65	130	
Latch Disable Pulse Width	t_{WH}	5	250	125	—	
		10	100	50	—	
		15	80	40	—	
Address Setup Time	t_{SU}	5	60	15	—	
		10	20	–5	—	
		15	10	–5	—	
Address Hold Time	t_H	5	25	–5	—	
		10	20	10	—	
		15	20	10	—	
Input Capacitance	C_{IN}	Any Input	—	5	7.5	pF

92CS-34515

Fig. 4 – BCD-to-seven-segment latch/decoder/driver functional diagram.

92CS-2431BR3

Fig. 5 – Typical output low (sink) current characteristics.

92CS-24319RI

Fig. 6 – Minimum output low (sink) current characteristics.

CD4543B Types

TRUTH TABLE FOR CD4543B

INPUT CODE							OUTPUT STATE							DISPLAY CHAR-ACTER
LD	BI	Ph*	D	C	B	A	a	b	c	d	e	f	g	
X	1	0	X	X	X	X	0	0	0	0	0	0	0	
1	0	0	0	0	0	0	1	1	1	1	1	1	0	0
1	0	0	0	0	0	1	0	1	1	0	0	0	0	1
1	0	0	0	0	1	0	1	1	0	1	1	0	1	2
1	0	0	0	0	1	1	1	1	1	1	0	0	1	3
1	0	0	0	1	0	0	0	1	1	0	0	1	1	4
1	0	0	0	1	0	1	1	0	1	1	0	1	1	5
1	0	0	0	1	1	0	1	0	1	1	1	1	1	6
1	0	0	0	1	1	1	1	1	1	0	0	0	0	7
1	0	0	1	0	0	0	1	1	1	1	1	1	1	8
1	0	0	1	0	0	1	1	1	1	1	0	1	1	9
1	0	0	1	0	1	0	0	0	0	0	0	0	0	Blank
1	0	0	1	0	1	1	0	0	0	0	0	0	0	Blank
1	0	0	1	1	0	0	0	0	0	0	0	0	0	Blank
1	0	0	1	1	0	1	0	0	0	0	0	0	0	Blank
1	0	0	1	1	1	0	0	0	0	0	0	0	0	Blank
1	0	0	1	1	1	1	0	0	0	0	0	0	0	Blank
0	0	0	X	X	X	X	**							**
†	†	1	†				Inverse of Output Combinations Above							Display as above

X=Don't care.

†=Above combinations.

*=For liquid-crystal readouts, apply a square wave to Ph.

   For common cathode LED readouts, select Ph=0.

   For common anode LED readouts, select Ph=1.

**=Depends upon the BCD code previously applied when LD=1.

Fig. 7 - Typical transition time as a function of load capacitance.
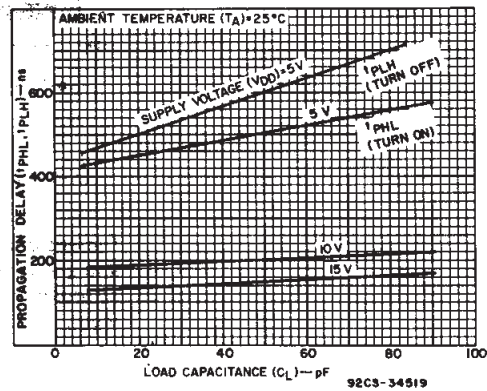

Fig. 8 - Typical propagation delay time as a function of load capacitance.

Fig. 9 – Typical dynamic power dissipation as a function of frequency.

Fig. 10 – Quiescent device current test circuit.
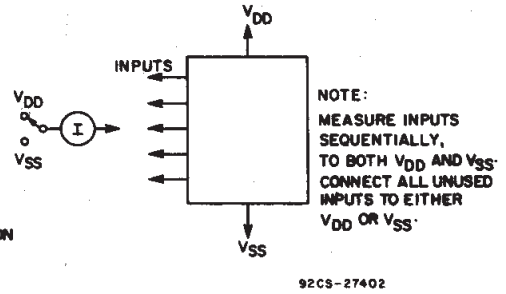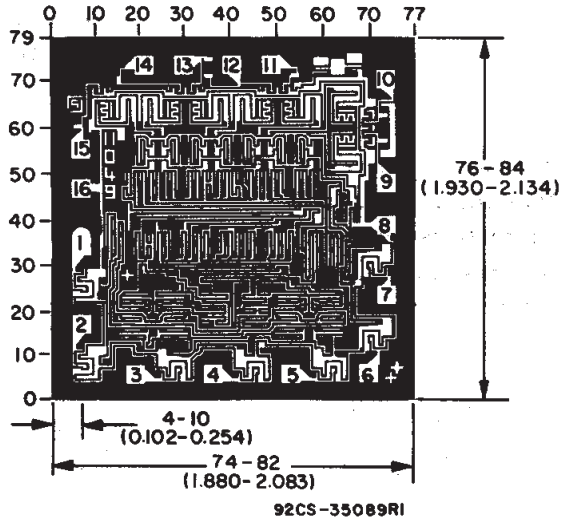
Fig. 11 – Input voltage test circuit.

Fig. 12 – Input current test circuit.

NOTE:
TEST ANY COMBINATION
OF INPUTS

NOTE:
MEASURE INPUTS
SEQUENTIALLY,
TO BOTH V_{DD} AND V_{SS}.
CONNECT ALL UNUSED
INPUTS TO EITHER
V_{DD} OR V_{SS}.

76–84
(1.930–2.134)

4–10
(0.102–0.254)

74–82
(1.880–2.083)

92CS-35089RI

Dimensions and pad layout for CD4543BH.

Dimensions in parentheses are in millimeters
and are derived from the basic inch dimensions
as indicated. Grid graduations are in mils $(10^{-3}$
inch).

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
CD4543BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4543BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4543BM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4543BM96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4543BM96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4543BME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4543BMT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4543BMTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4543BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4543BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4543BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4543BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4543BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4543BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

[1] The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is

provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.
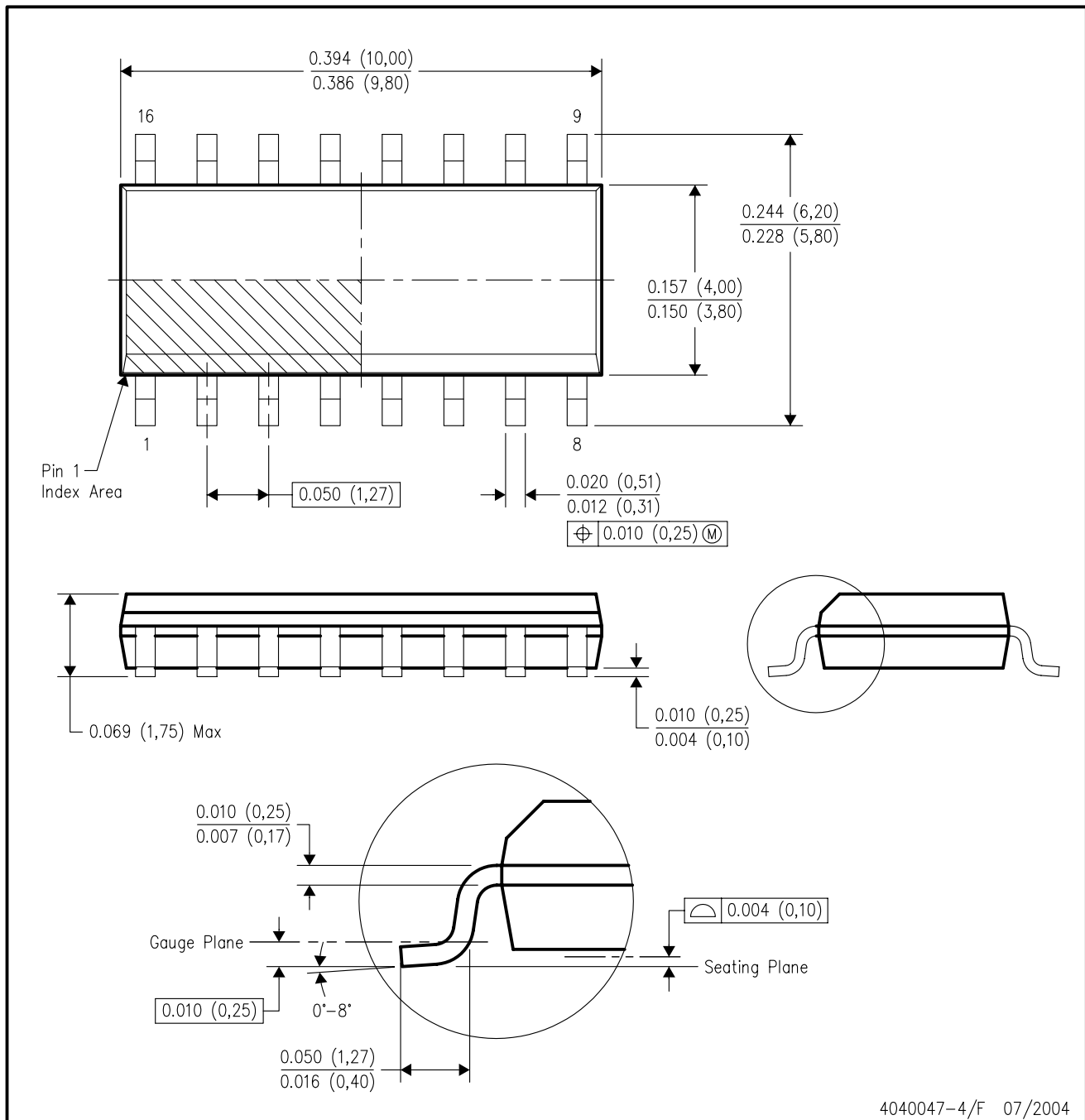
N (R−PDIP−T**)

PLASTIC DUAL−IN−LINE PACKAGE

16 PINS SHOWN

DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS−001 VARIATION	AA	BB	AC	AD

0.260 (6,60) / 0.240 (6,10)

0.070 (1,78) / 0.045 (1,14) △D

0.045 (1,14) / 0.030 (0,76) △D

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53) / 0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

14/18 Pin Only
20 Pin vendor option △D

0.325 (8,26) / 0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

4040049/E   12/2002

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         △C   Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
         △D   The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R−PDSO−G16) PLASTIC SMALL−OUTLINE PACKAGE

0.394 (10,00)
0.386 (9,80)

16

9

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80)

1

8

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.007 (0,17)

0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)

0°−8°

0.050 (1,27)
0.016 (0,40)
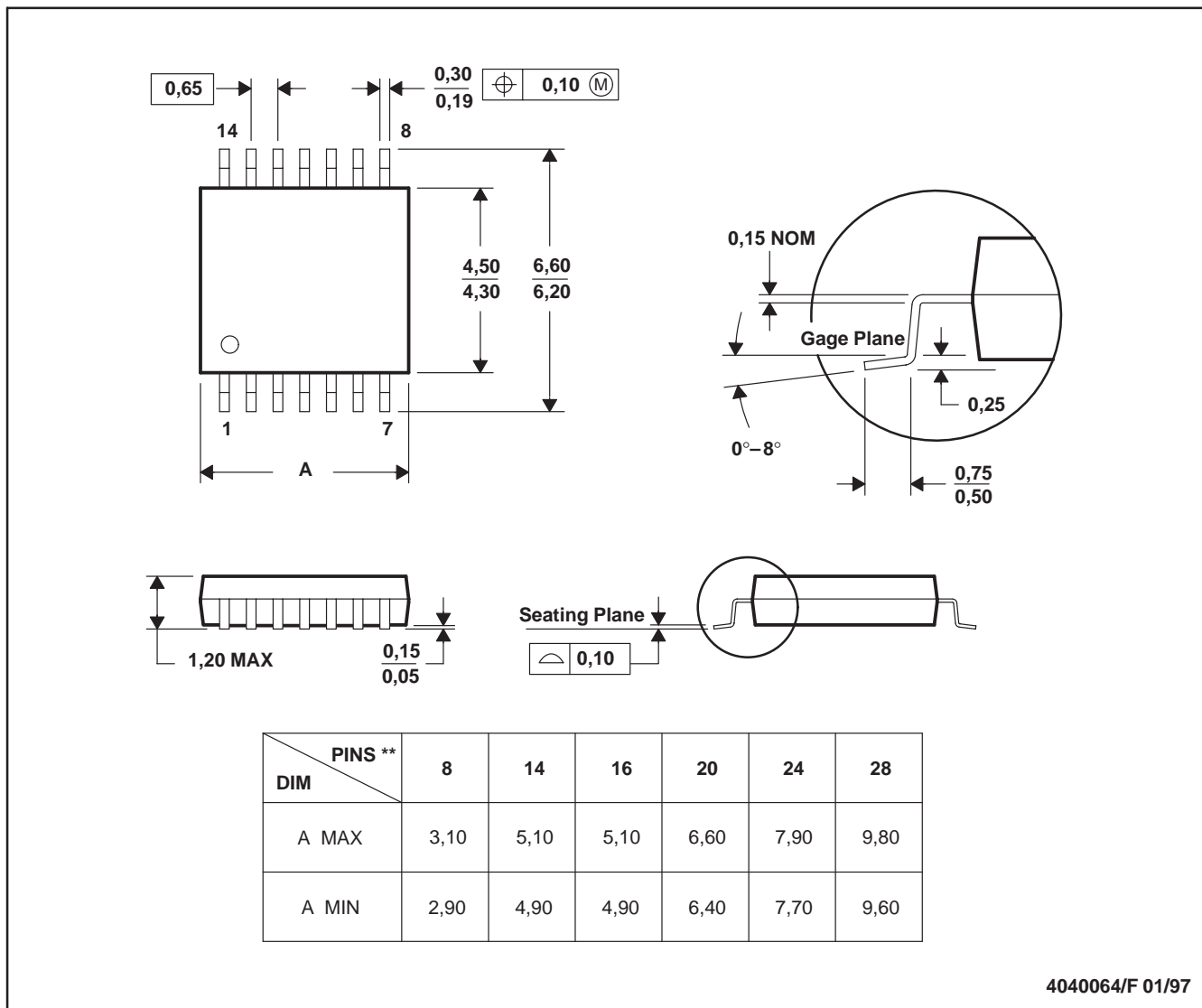
4040047−4/F 07/2004

NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
        D. Falls within JEDEC MS−012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

DIM / PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A.   All linear dimensions are in millimeters.
   B.   This drawing is subject to change without notice.
   C.   Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN

	PINS **	8	14	16	20	24	28
DIM							
A MAX		3,10	5,10	5,10	6,60	7,90	9,80
A MIN		2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

![Texas Instruments logo]

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		**Applications**	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments
                    Post Office Box 655303 Dallas, Texas 75265